

## HI-8282

September 2006

ARINC 429 SERIAL TRANSMITTER AND DUAL RECEIVER

## **GENERAL DESCRIPTION**

The HI-8282 is a silicon gate CMOS device for interfacing the ARINC 429 serial data bus to a 16-bit parallel data bus. Two receivers and an independent transmitter are provided. The receiver input circuitry and logic are designed to meet the ARINC 429 specifications for loading, level detection, timing, and protocol. The transmitter section provides the ARINC 429 communication protocol. An external line driver such as the Holt HI-8585 or HI-3182 is required to translate the 5 volt logic outputs to ARINC 429 drive levels.

The 16-bit parallel data bus exchanges the 32-bit ARINC data word in two steps when either loading the transmitter or interrogating the receivers. The data bus interfaces with CMOS and TTL.

Timing of all the circuitry begins with the master clock input, CLK. For ARINC 429 applications, the master clock frequency is 1 MHz.

Each independent receiver monitors the data stream with a sampling rate 10 times the data rate. The sampling rate is software selectable at either 1MHz or 125KHz. The results of a parity check are available as the 32nd ARINC bit. The HI-8282 examines the null and data timings and will reject erroneous patterns. For example, with a 125 KHz clock selection, the data frequency must be between 10.4 KHz and 15.6 KHz.

The transmitter has a First In, First Out (FIFO) memory to store 8 ARINC words for transmission. The data rate of the transmitter is software selectable by dividing the master clock, CLK, by either 10 or 80. The master clock is used to set the timing of the ARINC transmission within the required resolution.

## **APPLICATIONS**

- Avionics data communication
- Serial to parallel conversion
- Parallel to serial conversion

## FEATURES

- ARINC specification 429 compliant
- 16-Bit parallel data bus
- Direct receiver interface to ARINC bus
- Timing control 10 times the data rate
- Selectable data clocks
- Receiver error rejection per ARINC specification 429
- Automatic transmitter data timing
- Self test mode
- Parity functions
- Low power, single 5 volt supply
- Industrial & full military temperature ranges
- DSCC SMD part number

## PIN CONFIGURATION (Top View)

Vcc <b>f</b>	1	40	Ь ис
(REC. 1 INPUT) 429DI1(A) 🖞	2	39	THE MASTER RESET)
(REC.1 INPUT) 429DI1(B) <b>4</b>	3	38	TX CLK (XMIT CLOCK OUT)
(REC. 2 INPUT) 429DI2(A)	4	37	CLK (MASTER CLK IN)
(REC. 2 INPUT) 429DI2(B) <b>4</b>	5	36	D NC
(REC.1 DATA FLAG) D/R1	6	35	D NC
(REC.2 DATA FLAG) D/R2	7	34	CWSTR (CONTROL WORD STROBE)
(REC. BYTE SELECT) SEL 🗲	8	33	ENTX (ENABLE XMIT)
(REC. 1 OUTPUT ENABLE) EN1	9	32	A29DO (XMIT DATA)
(REC. 2 OUTPUT ENABLE) EN2	10	31	A29DO (XMIT DATA)
BD15 <b>੯</b>	11	30	TX/R (XMIT READY FLAG)
BD14 <b>੯</b>	12	29	PL2 (XMIT BYTE 2 LE)
BD13 <b>4</b>	13	28	PL1 (XMIT BYTE 1 LE)
BD12 <b>4</b>	14	27	р вD00
BD11 <b>4</b>	15	26	<b>B</b> D01
BD10 <b>4</b>	16	25	<b>P</b> BD02
BD09 <b>੯</b>	17	24	<b>P</b> BD03
BD08 <b>੯</b>	18	23	BD04
BD07 <b>੯</b>	19	22	BD05
BD06 <b>੯</b>	20	21	GND

### HI-8282C / CT / CM-01 / CM-03 SMD # 5962-8688002QA

40-Pin Ceramic Side-Brazed DIP (See page 10 for additional Package Pin Configurations)

## **PIN DESCRIPTION**

SYMBOL	FUNCTION	DESCRIPTION
VCC	POWER	+5V ±5%
429DI1 (A)	INPUT	ARINC receiver 1 positive input
429DI1 (B)	INPUT	ARINC receiver 1 negative input
429DI2 (A)	INPUT	ARINC receiver 2 positive input
429DI2 (B)	INPUT	ARINC receiver 2 negative input
D/R1	OUTPUT	Receiver 1 data ready flag
D/R2	OUTPUT	Receiver 2 data ready flag
SEL	INPUT	Receiver data byte selection (0 = BYTE 1) (1 = BYTE 2)
EN1	INPUT	Data Bus control, enables receiver 1 data to outputs
EN2	INPUT	Data Bus control, enables receiver 2 data to outputs if $\overline{EN1}$ is high
BD15	I/O	Data Bus
BD14	I/O	Data Bus
BD13	I/O	Data Bus
BD12	I/O	Data Bus
BD11	I/O	Data Bus
BD10	I/O	Data Bus
BD09	I/O	Data Bus
BD08	I/O	Data Bus
BD07	I/O	Data Bus
BD06	I/O	Data Bus
GND	POWER	0 V
BD05	I/O	Data Bus
BD04	I/O	Data Bus
BD03	I/O	Data Bus
BD02	I/O	Data Bus
BD01	I/O	Data Bus
BD00	I/O	Data Bus
PL1	INPUT	Latch enable for byte 1 entered from data bus to transmitter FIFO.
PL2	INPUT	Latch enable for byte 2 entered from data bus to transmitter FIFO. Must follow $\overline{PL1}$ .
TX/R	OUTPUT	Transmitter ready flag. Goes low when ARINC word loaded into FIFO. Goes high after transmission and FIFO empty.
429DO	OUTPUT	"ONES" data output from transmitter.
429DO	OUTPUT	"ZEROES" data output from transmitter.
ENTX	INPUT	Enable Transmission
CWSTR	INPUT	Clock for control word register
CLK	INPUT	Master Clock input
TX CLK	OUTPUT	Transmitter Clock equal to Master Clock (CLK), divided by either 10 or 80.
MR	INPUT	Master Reset, active low

## FUNCTIONAL DESCRIPTION

#### CONTROL WORD REGISTER

The HI-8282 contains 10 data flip flops whose D inputs are connected to the data bus and clocks connected to CWSTR. Each flip flop provides options to the user as follows:

DATA BUS PIN	FUNCTION	CONTROL	DESCRIPTION		
BDO5	SELF TEST	0 = ENABLE	If enabled, an internal connection is made passing 429DO and 429DO to the receiver logic inputs		
BDO6	RECEIVER 1 DECODER	1 = ENABLE	If enabled, ARINC bits 9 and, 10 must match the next two control word bits		
BDO7	-	-	If Receiver 1 Decoder is enabled, the ARINC bit 9 must match this bit		
BDO8			If Receiver 1 Decoder is enabled, the ARINC bit 10 must match this bit		
BDO9	RECEIVER 2 DECODER	1 = ENABLE	If enabled, ARINC bits 9 and 10 must match the next two control word bits		
BD10	-	-	If Receiver 2 Decoder is enabled, then ARINC bit 9 must match this bit		
BD11	-	-	If Receiver 2 Decoder is enabled, then ARINC bit 10 must match this bit		
BD12	INVERT XMTR PARITY	1 = ENABLE	Logic 0 enables normal odd parity and Logic 1 enables even parity output in transmitter 32nd bit		
BD13	XMTR DATA CLK SELECT	0 = ÷10 1 = ÷80	CLK is divided either by 10 or 80 to obtain XMTR data clock		
BD14	RCVR DTA CLK SELECT	0 = ÷10 1 = ÷80	CLK is divided either by 10 or 80 to obtain RCVR data clock		

#### **ARINC 429 DATA FORMAT**

The following table shows the bit positions in exchanging data with the receiver or the transmitter. ARINC bit 1 is the first bit transmitted or received.

					B	ΥΤΕ	E 1									
DATA BUS	BD 15	BD 14	BD 13	BD 12	BD 11	BD 10	BD 09	BD 08	BD 07	BD 06	BD 05		1	BD 02	BD 01	BD 00
ARINC BIT	13	12	11	10	9	31	30	32	1	2	3	4	5	6	7	8

					B	YTE	2									
DATA BUS	BD 15	BD 14	BD 13	BD 12	BD 11			BD 08	BD 07		BD 05	BD 04	BD 03	BD 02	BD 01	BD 00
ARINC BIT	29	28	27	26	25	24	23	22	21	20	19	18	17	16	15	14

#### **THE RECEIVERS**

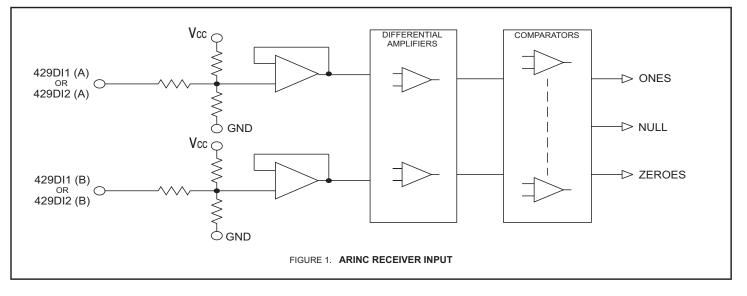
#### **ARINC BUS INTERFACE**

Figure 1 shows the input circuit for each receiver. The ARINC 429 specification requires the following detection levels:

<b>STATE</b>	DIFFERENTIAL VOLTAGE	
ONE	+6.5 Volts to +13 Volts	
NULL	+2.5 Volts to -2.5 Volts	
ZERO	-6.5 Volts to -13 Volts	

The HI-8282 guarantees recognition of these levels with a common mode Voltage with respect to GND less than  $\pm 4V$  for the worst case condition (4.75V supply and 13v signal level).

The tolerances in the design guarantee detection of the above levels, so the actual acceptance ranges are slightly larger. If the ARINC signal is out of the actual acceptance ranges, including the nulls, the chip rejects the data.



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## FUNCTIONAL DESCRIPTION (cont.)

#### **RECEIVER LOGIC OPERATION**

Figure 2 shows a block diagram of the logic section of each receiver.

#### **BIT TIMING**

The ARINC 429 specification contains the following timing specification for the received data:

	HIGH SPEED	LOW SPEED
BIT RATE	100K BPS ± 1%	12K -14.5K BPS
PULSE RISE TIME	1.5 ± 0.5 µsec	10 ± 5 µsec
PULSE FALL TIME	1.5 ± 0.5 µsec	10 ± 5 µsec
PULSE WIDTH	5 µsec ± 5%	34.5 to 41.7 µsec

The HI-8282 accepts signals that meet these specifications and rejects outside the tolerances. The way the logic operation achieves this is described below:

1. Key to the performance of the timing checking logic is an accurate 1MHz clock source. Less than 0.1% error is recommended.

2. The sampling shift registers are 10 bits long and must show three consecutive Ones, Zeros or Nulls to be considered valid data. Additionally, for data bits, the One or Zero in the upper bits of the sampling shift registers must be followed by a Null in the lower bits within the data bit time. For a Null in the word gap, three consecutive Nulls must be found in both the upper and lower bits of the sampling shift register. In this manner the minimum pulse width is guaranteed.

3. Each data bit must follow its predecessor by not less than 8 samples and no more than 12 samples. In this manner the bit rate is checked. With exactly 1MHz input clock frequency, the acceptable data bit rates are as follows:

	<u>HIGH SPEED</u>	LOW SPEED
DATA BIT RATE MIN	83K BPS	10.4K BPS
DATA BIT RATE MAX	125K BPS	15.6K BPS

4. The Word Gap timer samples the Null shift register every 10 input clocks (80 for low speed) after the last data bit of a valid reception. If the Null is present, the Word Gap counter is incremented. A count of 3 will enable the next reception.

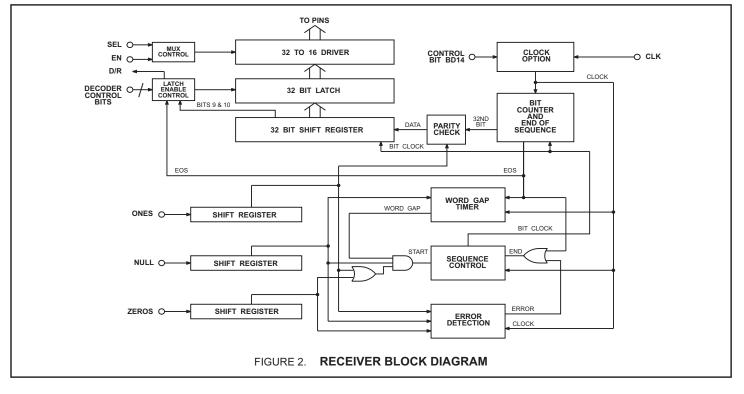
#### **RECEIVER PARITY**

The receiver parity circuit counts Ones received, including the parity bit, ARINC bit 32. If the result is odd, then "0" will appear in the 32nd bit.

#### **RETRIEVING DATA**

Once 32 valid bits are recognized, the receiver logic generates an End of Sequence (EOS). If the receiver decoder is enabled and the 9th and 10th ARINC bits match the control word program bits or if the receiver decoder is disabled, then EOS clocks the data ready flag flip flop to a "1", D/R1 or D/R2 (or both) will go low. The data flag for a receiver will remain low until after both ARINC bytes from that receiver are retrieved. This is accomplished by activating EN with SEL, the byte selector, low to retrieve the first byte and activating EN with SEL high to retrieve the second byte. EN1 retrieves data from receiver 1 and EN2 retrieves data from receiver 2.

If another ARINC word is received and a new EOS occurs before the two bytes are retrieved, the data is overwritten by the new word.



## **FUNCTIONAL DESCRIPTION (cont.)**

#### TRANSMITTER

A block diagram of the transmitter section is shown in Figure 3.

#### **FIFO OPERATION**

The FIFO is loaded sequentially by first pulsing  $\overline{PL1}$  to load byte 1 and then  $\overline{PL2}$  to load byte 2. The control logic automatically loads the 31 bit word in the next available position of the FIFO. If TX/R, the transmitter ready flag, is high (FIFO empty), then 8 words, each 31 bits long, may be loaded. If TX/R is low, then only the available positions may be loaded. If all 8 positions are full, the FIFO ignores further attempts to load data.

#### DATA TRANSMISSION

When ENTX goes high, enabling transmission, the FIFO positions are incremented with the top register loading into the data transmission shift register. Within 2.5 data clocks the first data bit appears at either 429DO or 429DO. The 31 bits in the data transmission shift register are presented sequentially to the outputs in the ARINC 429 format with the following timing:

	HIGH SPEED	LOW SPEED
ARINC DATA BIT TIME	10 Clocks	80 Clocks
DATA BIT TIME	5 Clocks	40 Clocks
NULL BIT TIME	5 Clocks	40 Clocks
WORD GAP TIME	40 Clocks	320 Clocks

The word counter detects when all loaded positions are transmitted and sets the transmitter ready flag, TX/R, high.

#### **TRANSMITTER PARITY**

The parity generator counts the ONES in the 31-bit word. If the BD12 control word bit is set low, the 32nd bit transmitted will make parity odd. If the control bit is high, the parity is even.

#### SELF TEST

If the BD05 control word bit is set low, the digital outputs of the transmitter are internally connected to the logic inputs of the receivers, bypassing the analog bus interface circuitry. Data to Receiver 1 is as transmitted and data to Receiver 2 is the complement. All data transmitted during self test is also present on the TXA(OUT) and TXB(OUT) line driver outputs.

#### SYSTEM OPERATION

The two receivers are independent of the transmitter. Therefore, control of data exchanges is strictly at the option of the user. The only restrictions are:

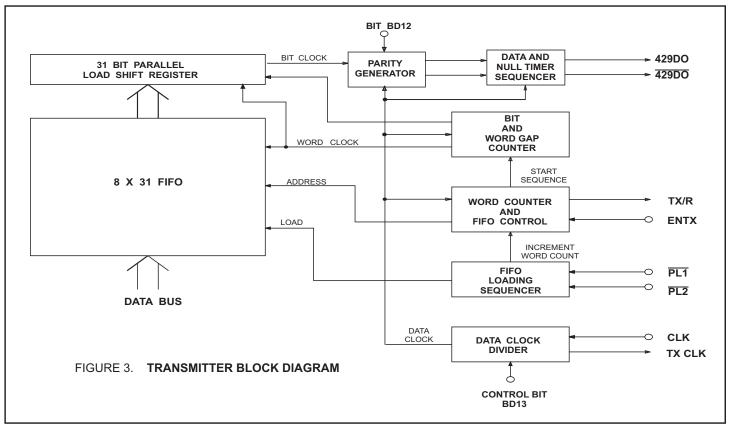
1. The received data may be overwritten if not retrieved within one ARINC word cycle.

2. The FIFO can store 8 words maximum and ignores attempts to load addition data if full.

3. Byte 1 of the transmitter data must be loaded first.

4. Either byte of the received data may be retrieved first. Both bytes must be retrieved to clear the data ready flag.

5. After ENTX, transmission enable, goes high it cannot go low until TX/R, transmitter ready flag, goes high. Otherwise, one ARINC word is lost during transmission.



## FUNCTIONAL DESCRIPTION (cont.)

#### **REPEATER OPERATION**

he repeater mode of operation allows a data word that has been received by the HI-8282 to be placed directly into its FIFO for transmission. After a 32-bit word has been shifted into Tthe receiver shift register, the  $\overline{D/R}$  flag will go low. A logic "0" is placed on the SEL line and  $\overline{EN}$  is strobed. This is the same procedure as for normal receiver operation and it places the lower byte (16) of the data word on the data bus. By strobing  $\overline{PL1}$  at the same time as  $\overline{EN}$ ,

the byte will also be placed into the transmitter FIFO. SEL is then taken high and  $\overline{EN}$  is strobed again to place the upper byte of the data word on the data bus. By strobing  $\overline{PL2}$  at the same time as  $\overline{EN}$ , the second byte will also be placed into the FIFO. The data word is

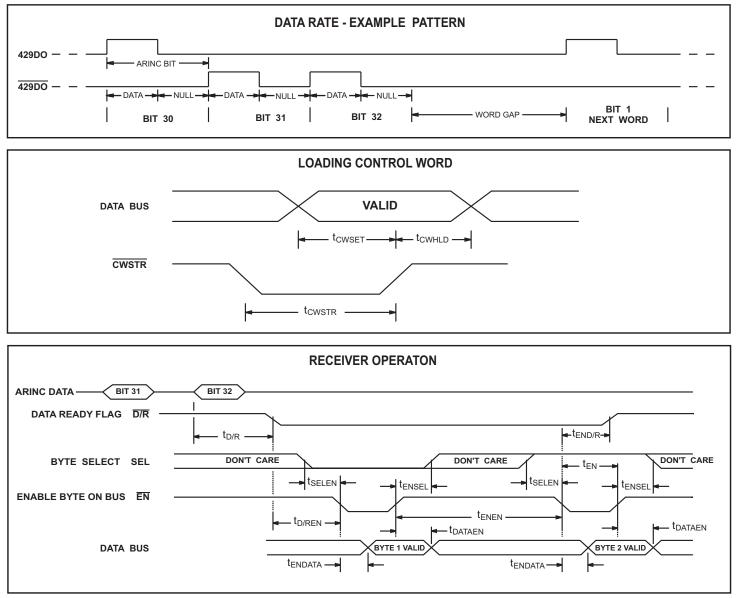
now ready to be transmitted according to the parity programmed into the control word register.

In normal operation, either byte of a received data word may be read from the receiver latches first by use of SEL input. During repeater operation however, the lower byte of the data word must be read first. This is necessary because, as the data is being read, it is also being loaded into the FIFO and the transmitter FIFO is always loaded with the lower byte of the data word first.

#### MASTER RESET (MR)

On a Master Reset data transmission and reception are immediately terminated, all three FIFOs are cleared as are the FIFO flags at the device pins and in the Status Register. The Control Register is not affected by a Master Reset.

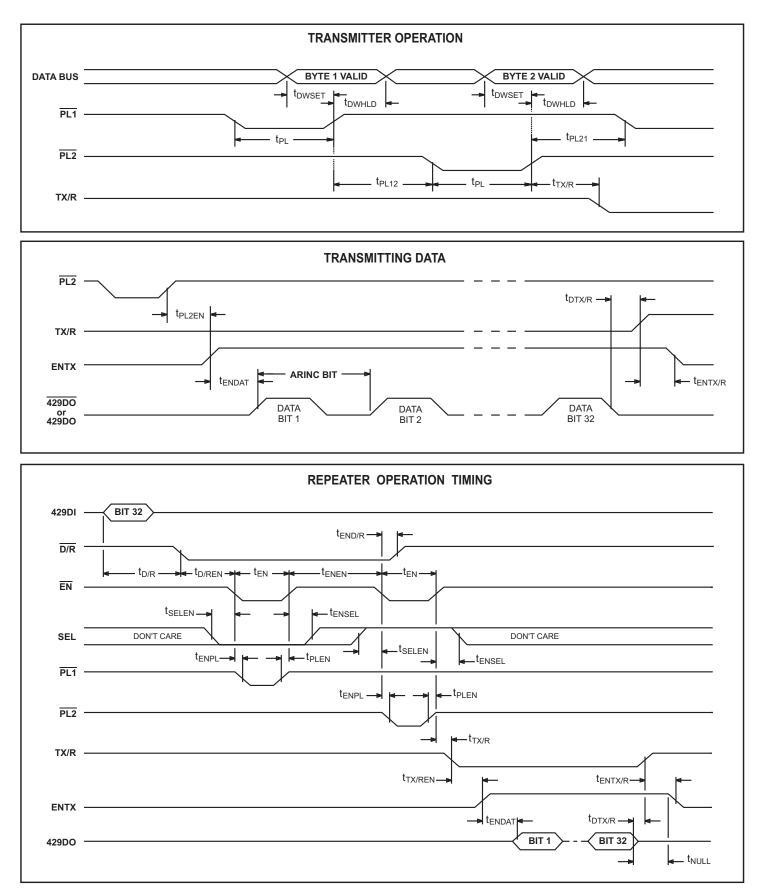
## TIMING DIAGRAMS



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HI-8282

## **TIMING DIAGRAMS (cont.)**



## **ABSOLUTE MAXIMUM RATINGS**

Supply Voltage Vcc	Power Dissipation 500mW
Voltage at ARINC input pins29V to +29V	Operating Temperature Range: (Industrial)40°C to +85°C
Voltage at any other pin0.3V to Vcc +0.3V	(Military) · · · · · 55°C to +125°C
DC Current Drain per input pin 10mA	Storage Temperature Range:

NOTE: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only. Functional operation of the device at these or any other conditions above those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

## **DC ELECTRICAL CHARACTERISTICS**

Vcc = 5V ±5%, GND = 0V, TA = Operating Temperature Range (unless otherwise specified).

					LIMITS		
PARAMETE	ER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNIT
ARINC INPUTS							
Differential Input Voltage:	ONE ZERO NULL	Vih Vil Vnul	Pins 2 to 3, 4 to 5: Common mode voltage less than ±4V with respect to GND	6.5 -13.0 -2.5	10.0 -10.0 0	13.0 -6.5 2.5	V V V
Input Resistance:	Differential To GND To Vcc	Ri Rg Rн		12 12 12	27 27		KΩ KΩ kΩ
Input Current:	Input Sink Input Source	liн li∟		-450		200	μΑ μΑ
Input Capacitance: (Guaranteed but not tested)	Differential To GND To Vcc	Сі Сд Сн	Pins 2 to 3, 4 to 5			20 20 20	pF pF pF
<b>BI-DIRECTIONAL INPUTS</b>							
Input Voltage:	Input Voltage HI Input Voltage LO	Vih Vil		2.1		0.7	V V
Input Current:	Input Sink Input Source	liн li∟		-1.5		1.5	μA μA
ALL OTHER INPUTS							
Input Voltage:	Input Voltage HI Input Voltage LO	Vih Vil		3.5		0.7	V V
Input Current:	Input Sink Input Source	liн li∟		-20		10	μΑ μΑ
OUTPUTS							
Output Voltage:	Logic "1" Output Voltage Logic "0" Output Voltage	Vон Vol	Iон = -1.5mA Iо∟ = 1.8mA	2.7		0.4	V V
Output Current: (Bi-directional Pins)	Output Sink Output Source	Iol Ioн	Vout = 0.4V Vout = Vcc - 0.4V	3.0 1.5			mA mA
Output Current: (All Other Outputs)	Output Sink Output Source	Iol Ioн	Vout = 0.4V Vout = Vcc - 0.4V	3.6 1.5			mA mA
Output Capacitance:		Co				15	pF
SUPPLY INPUT							
Standby Supply Current:		Icc1				20	mA
Operating Supply Current:		ICC2				20	mA

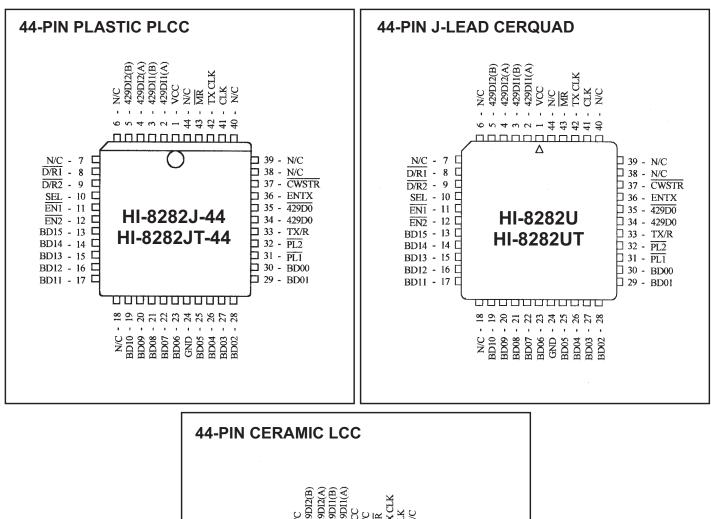
## AC ELECTRICAL CHARACTERISTICS

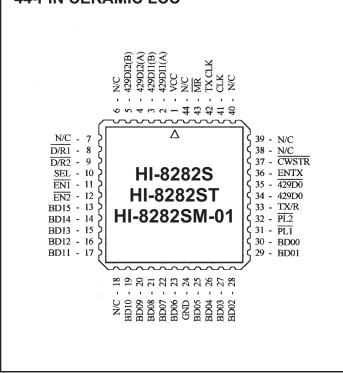
Vcc = 5V, GND = 0V, TA = Operating Temperature Range and fclk = 1MHz +0.1% with 60/40 duty cycle

DADAMETED					
PARAMETER	SYMBOL	MIN	ТҮР	MAX	UNITS
CONTROL WORD TIMING				-	1
Pulse Width - CWSTR Setup - DATA BUS Valid to CWSTR HIGH Hold - CWSTR HIGH to DATA BUS Hi-Z	tcwstr tcwset tcwhLd	130 140 0			ns ns ns
RECEIVER TIMING					
Delay - Start ARINC 32nd Bit to D/R LOW: High Speed Low Speed	tD/R tD/R			16 128	μs μs
Delay - D/R LOW to EN L0W Delay - EN LOW to D/R HIGH	td/ren tend/r	0		200	ns ns
Setup - SEL to <del>EN</del> L0W Hold - SEL to <del>EN</del> HIGH	tselen tensel	20 50			ns ns
Delay - EN L0W to DATA BUS Valid Delay - EN HIGH to DATA BUS Hi-Z	tendata tdataen			200 30	ns ns
Pulse Width - EN1 or EN2 Spacing - EN HIGH to next EN LOW	ten tenen	240 50			ns ns
FIFO TIMING					
Pulse Width - PL1 or PL2	tPL	200			ns
Setup - DATA BUS Valid to PL HIGH Hold - PL HIGH to DATA BUS Hi-Z	tDWSET tDWHLD	110 20			ns ns
Spacing - PL1 to PL2	tPL12	0			ns
Spacing - PL2 to PL1	tPL21	250			ns
Delay - PL2 HIGH to TX/R LOW	ttx/R			840	ns
TRANSMISSION TIMING					
Spacing - PL2 HIGH to ENTX HIGH	<b>t</b> PL2EN	0			μs
Delay - ENTX HIGH to TXA(OUT) or TXB(OUT): High Speed Delay - ENTX HIGH to TXA(OUT) or TXB(OUT): Low Speed	tendat tendat			25 200	μs μs
Delay - 32nd ARINC Bit to TX/R HIGH	tdtx/r			400	ns
Spacing - TX/R HIGH to ENTX L0W	tentx/R	0			ns
REPEATER OPERATION TIMING					
Delay - EN LOW to PL LOW	tenpl	0			ns
Hold - PL HIGH to EN HIGH	<b>t</b> PLEN	0			ns
Delay - TX/R LOW to ENTX HIGH	ttx/ren	0			ns
Master Reset Pulse Width	tmr	400			ns
ARINC Data Rate and Bit Timing				± 1%	

## ADDITIONAL HI-8282 PIN CONFIGURATIONS

(See page 1 for the 40-pin Ceramic Side-Brazed DIP Package )





## **ORDERING INFORMATION**

#### HI - 8282 <u>x x - xx</u> (Ceramic)

 PART NUMBER	TEMPERATURE RANGE	FLOW	BURN IN
Blank	-40°C TO +85°C	I	NO
Т	-55°C TO +125°C	Т	NO
M-01	-55°C TO +125°C	М	YES
M-03 (1)	-55°C TO +125°C	DSCC	YES

 PART NUMBER	PACKAGE DESCRIPTION	LEAD FINISH (2)
С	40 PIN CERAMIC SIDE BRAZED DIP	Gold ('M' flow: solder)
S	44 PIN CERAMIC LEADLESS CHIP CARRIER	Gold ('M' flow: solder)
U	44 PIN CERQUAD (not available with 'M' flow)	Solder

## HI - <u>8282J x x</u> - 44 (Plastic)

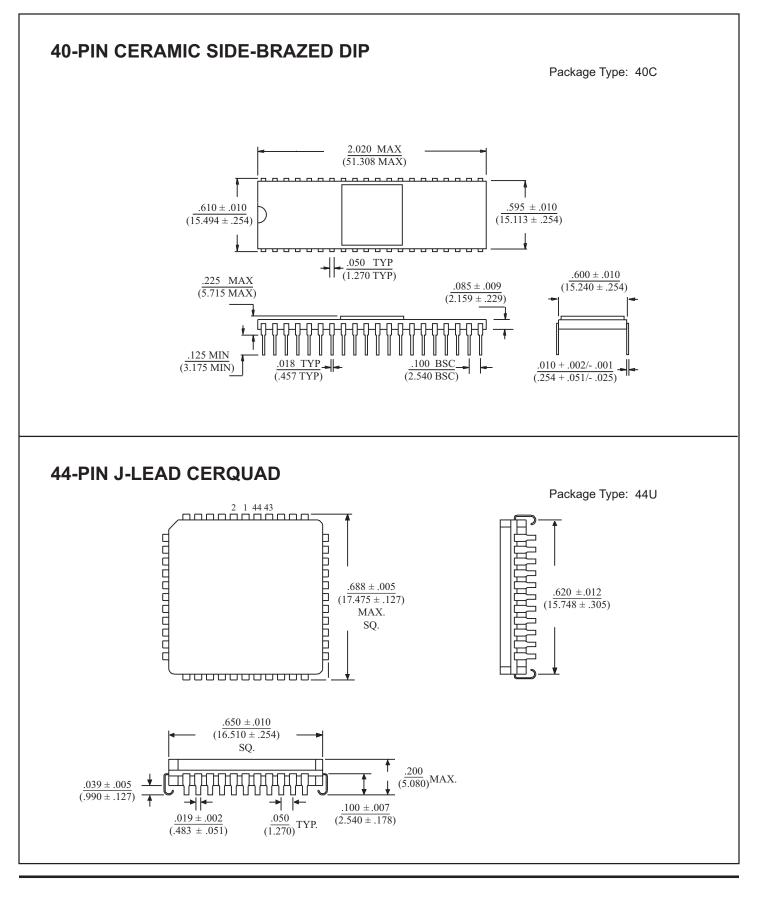
		PART NUMBER	LEAD FINISH				
		ROMBER					
		Blank	Tin / Lead (Sn / Pb) Solder				
		F	100% Matte Tin (Pb-free, RoHS compliant)				
		PART NUMBER	TEMPERATURE RANGE	FLOW	BURN IN		
		Blank	-40°C TO +85°C	I	NO		
		Т	-55°C TO +125°C	Т	NO		
PART PACKAGE NUMBER DESCRIPTION							
		8282J	44 PIN PLASTIC J LEAD (3)				

- (1) Only available in 'C' package. SMD# 5962-8688002QA
- (2) Gold terminal finish is Pb-Free, RoHS compliant.
- (3) NOT RECOMMENDED FOR NEW DESIGNS. The newer HI-8282APJI and HI-8282APJT replaces the HI-8282J-44 and HI-8282JT-44 respectively. The HI-8282A parts are rated as Moisture Sensitive Level 1 (MSL 1) and do not require any special handling. The older HI-8282J-44 and HI-8282JT-44 are rated as MSL 3 and require dry-packaging and /or bake-out in accordance with IPC/JEDEC J-STD-020A.

# INTEGRATED CIRCUITS

## **HI-8282 PACKAGE DIMENSIONS**

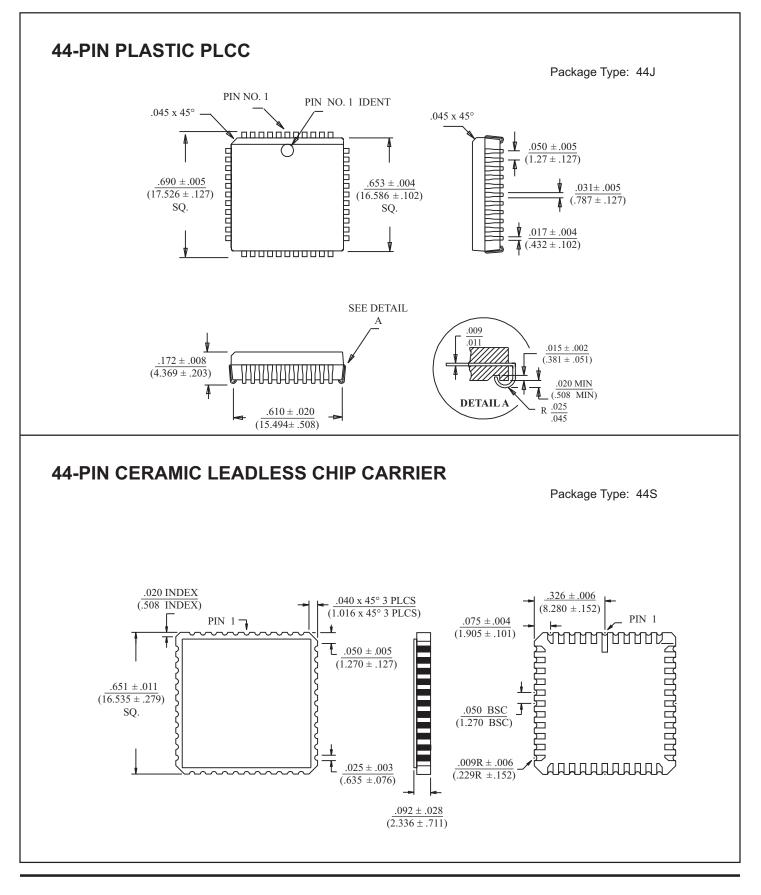
inches (millimeters)





## **HI-8282 PACKAGE DIMENSIONS**

inches (millimeters)



## HOLT INTEGRATED CIRCUITS 13